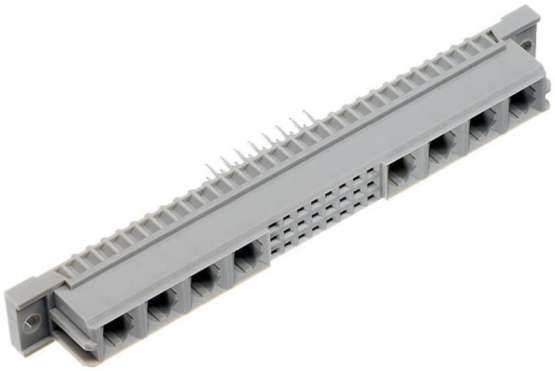
Product Data Sheet

DIN 41612 Straight-type M-series spring-loaded connector, Part No. 124-60012-00



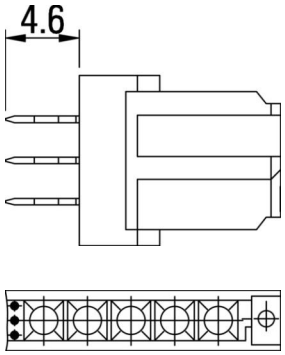


Illustration similar



Perpendicular | Press-fit | Power | Rugged

- Connector length: 4.6 mm
- Number of poles: 6 + 10
- Press-fit technology
- Grade 2

» to product on www.ept.de

» to product group DIN 41612

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Product Data Sheet

DIN 41612 Straight-type M-series spring-loaded connector, Part No. 124-60012-00

Technical Specifications

Basics

Specification	IEC 60603-2 (DIN 41612)
Performance Level	2
No. of Contacts	6 + 10
Termination Technology	Press-fit technology
Termination Length	4.6 mm
Operating Temperature Range	-55°C to +125°C

Material

Insulator Material	Glass-fiber-reinforced PBT, UL 94 V-0
CTI value *IEC 60112*	200
Contact Material	copper alloy

Mechanical

Pitch	2.54 mm
Mating Force	6 N
Separating Force per Pin	> 0.15 N
Durability	400 insertion cycles

Electrical

Operational Current	4.8 A
Test Voltage	1000 V
Contact Resistance	20 mΩ
Clearance and Creepage	≥ 1.2 mm
Insulation Resistance	$>10^6$ MΩ

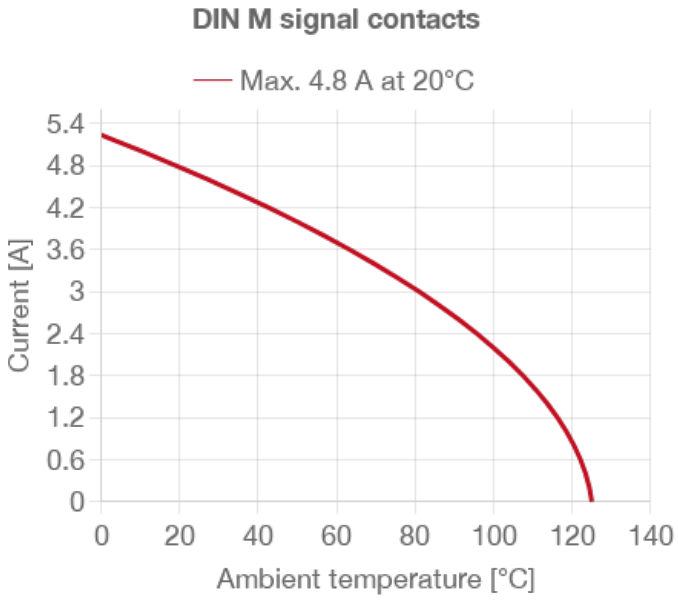
Approval / Compliance

UL file	E130314
Environment	RoHS compliant

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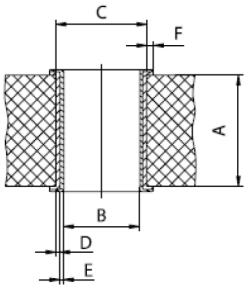
Derating Diagram



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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	chem. Sn Leiterplatten
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	chem. Sn Schicht, max. 1.5 µm
F Annular Ring	min. 0.1 mm

Material	Ni, Au Leiterplatten
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

Material	rein Cu Leiterplatten
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	OSP, z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm
F Annular Ring	min. 0.1 mm

Material	HAL Sn Leiterplatten
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min. 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	HAL Sn, 5 - 15 µm
F Annular Ring	min. 0.1 mm

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Modifications

Available on request

- without mounting flange
- Special lengths for connections
- Grade I + III or custom
- Special configuration

Drawings

Component data in 2D and 3D format you can download here:

» PDF » 3D IGES » 3D STEP » 3D PDF

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